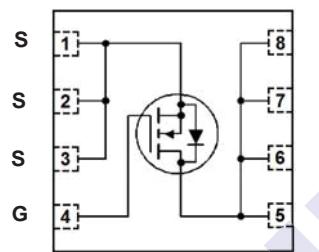


N-Channel MOSFET

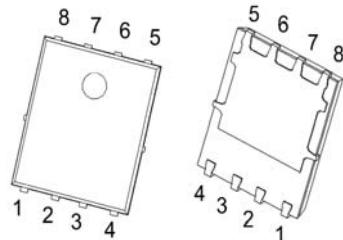
2KK5050DFN

■ Features

- V_{DS} (V) = 40 V
- I_D = 110 A
- $R_{DS(ON)}$ = 2.4 mΩ (typ.) @ $V_{GS}=10V$
- $R_{DS(ON)}$ = 3.3 mΩ (typ.) @ $V_{GS}=4.5V$



DFN5x6-8(PDFNWB5x6-8L)

■ Absolute Maximum Ratings ($T_C = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current	I_D	110	A
		77.8	
Pulsed Drain Current (Note 1)	I_{DM}	340	
Power Dissipation	P_D	75	W
Power Dissipation – Derate above 25°C		0.6	
Single Pulse Avalanche Energy (Note 2)	E_{AS}	500	mJ
Thermal Resistance, Junction- to-Case (Note 3)	$R_{\theta JC}$	1.67	°C/W
Junction Temperature	T_J	150	°C
Storage Temperature Range	T_{stg}	-55 to 150	

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. EAS condition : $T_J=25^\circ C$, $V_{DD}=20V$, $V_G=10V$, $L=0.5mH$, $R_g=25\Omega$
3. Surface Mounted on FR4 Board, $t \leq 10$ sec.

N-Channel MOSFET

2KK5050DFN

■ Electrical Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise specified)

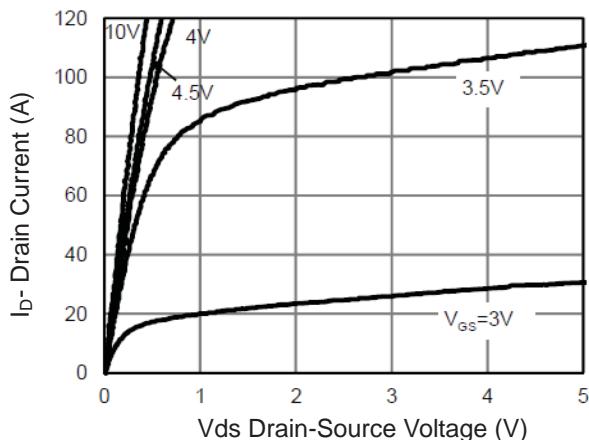
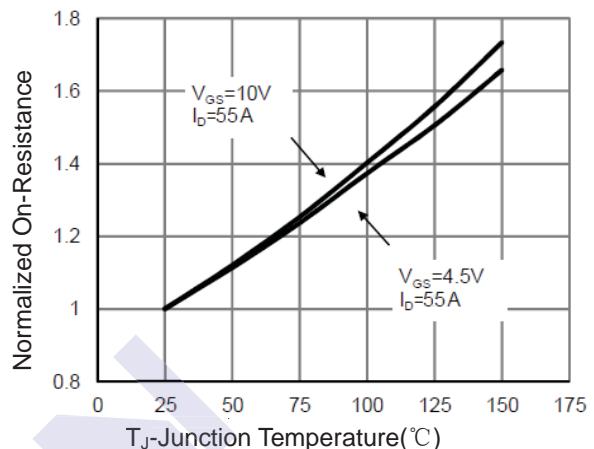
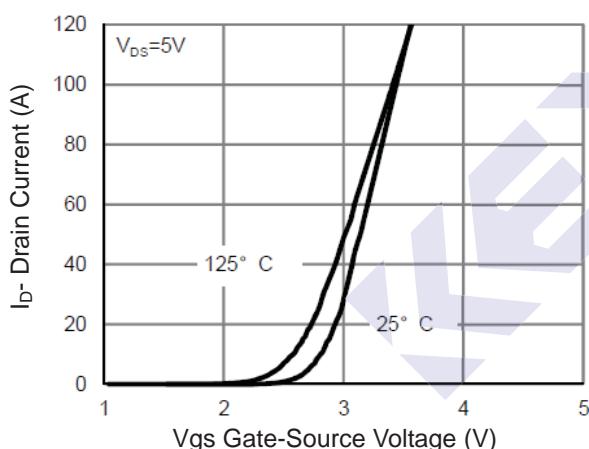
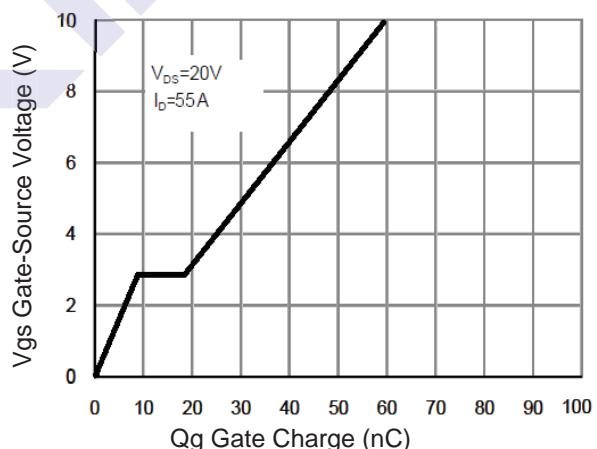
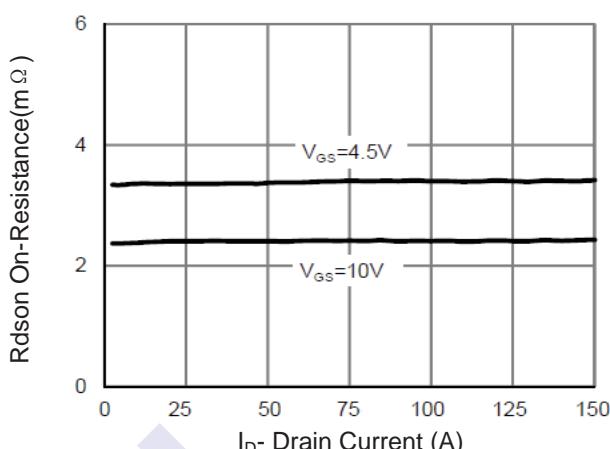
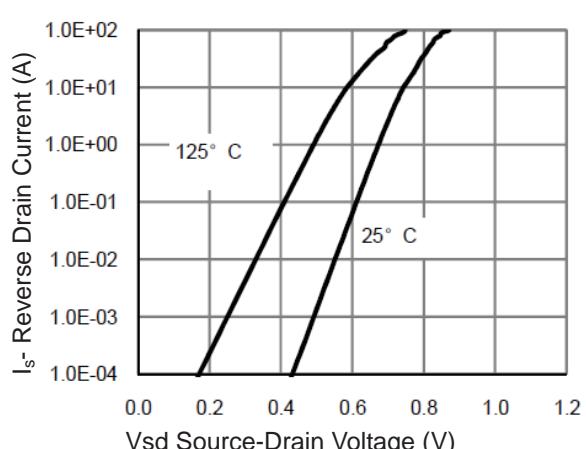
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$\text{Id} = 250 \mu\text{A}, \text{V}_{\text{GS}} = 0\text{V}$	40			V
Zero Gate Voltage Drain Current	I_{DSS}	$\text{V}_{\text{DS}} = 40 \text{ V}, \text{V}_{\text{GS}} = 0 \text{ V}$			1	μA
		$\text{V}_{\text{DS}} = 32 \text{ V}, \text{V}_{\text{GS}} = 0 \text{ V}, \text{T}_J=125^\circ\text{C}$			10	
Gate to Source Leakage Current	I_{GSS}	$\text{V}_{\text{DS}} = 0 \text{ V}, \text{V}_{\text{GS}} = \pm 20 \text{ V}$			± 100	nA
On Characteristics (Note 1)						
Gate to Source Threshold Voltage	$\text{V}_{\text{GS(th)}}$	$\text{V}_{\text{DS}} = \text{V}_{\text{GS}}, \text{Id} = 250\mu\text{A}$	1.2	1.7	2.2	V
Static Drain-Source On-Resistance	$\text{R}_{\text{DS(on)}}$	$\text{V}_{\text{GS}} = 10 \text{ V}, \text{Id} = 55 \text{ A}$		2.4	2.8	$\text{m}\Omega$
		$\text{V}_{\text{GS}} = 4.5 \text{ V}, \text{Id} = 55 \text{ A}$		3.3	3.9	
Forward Transconductance	g_{FS}	$\text{V}_{\text{DS}} = 5 \text{ V}, \text{Id} = 55 \text{ A}$		60		S
Dynamic Characteristics (Note 1)						
Input Capacitance	C_{iss}	$\text{V}_{\text{GS}} = 0 \text{ V}, \text{V}_{\text{DS}} = 20 \text{ V}, \text{f} = 1 \text{ MHz}$		3510		pF
Output Capacitance	C_{oss}			860		
Reverse Transfer Capacitance	C_{rss}			60		
Switching Characteristics (Note 1)						
Total Gate Charge	Q_g	$\text{V}_{\text{GS}} = 10 \text{ V}, \text{V}_{\text{DS}} = 20 \text{ V}, \text{Id} = 55 \text{ A}$		60		nC
Gate Source Charge	Q_{gs}			9.9		
Gate Drain Charge	Q_{gd}			5.5		
Turn-On Delay Time	$\text{t}_{\text{d(on)}}$	$\text{V}_{\text{GS}} = 10 \text{ V}, \text{V}_{\text{DD}} = 20 \text{ V}, \text{Id} = 55 \text{ A}, \text{R}_g = 1.6 \Omega$		10.5		ns
Turn-On Rise Time	t_{r}			4		
Turn-Off Delay Time	$\text{t}_{\text{d(off)}}$			35		
Turn-Off Fall Time	t_{f}			5		
Drain-Source Diode Characteristics						
Body Diode Reverse Recovery Time	t_{rr}	$\text{I}_{\text{s}} = 55 \text{ A}, \text{di/dt} = 100 \text{ A}/\mu\text{s}$		24		ns
Body Diode Reverse Recovery Charge	Q_{rr}			68		
Maximum Body-Diode Continuous Current	I_{s}				110	A
Diode Forward Voltage	V_{SD}	$\text{V}_{\text{GS}} = 0 \text{ V}, \text{I}_{\text{s}} = 55 \text{ A}$			1.2	V

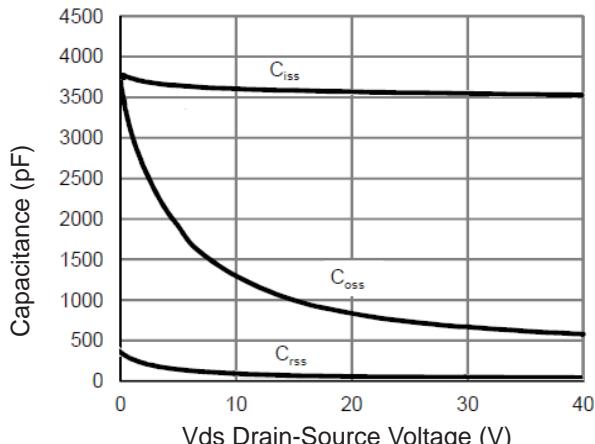
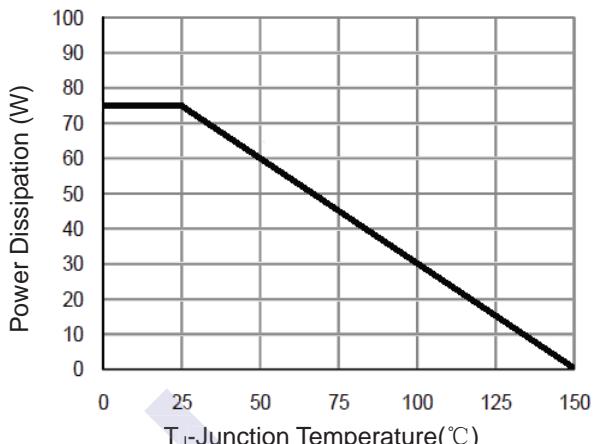
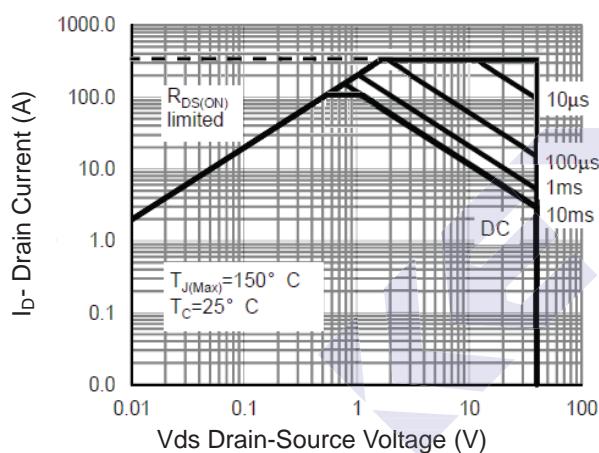
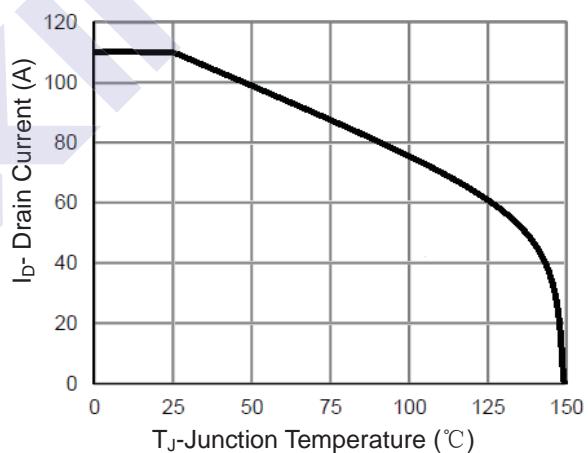
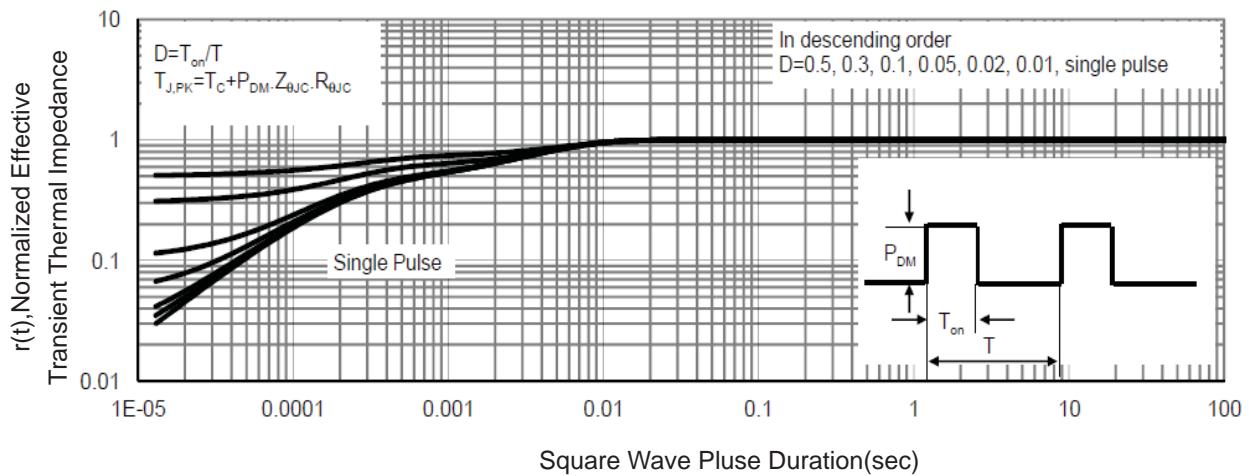
Notes:

1. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.

■ Marking

Marking	K5050 KC***
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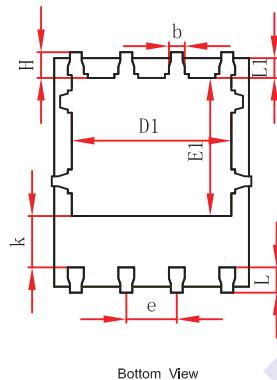
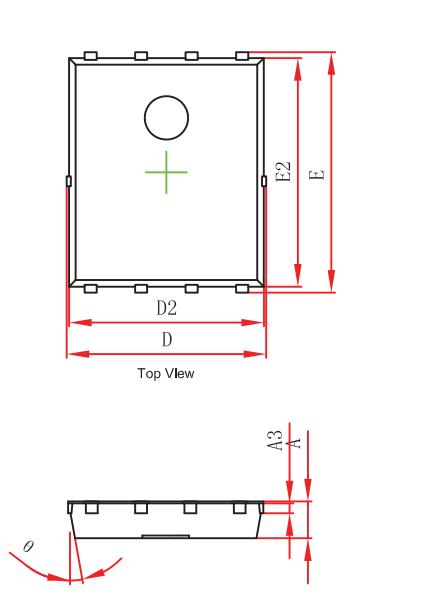
N-Channel MOSFET**2KK5050DFN****■ Typical Electrical Characteristics****Figure 1 Output Characteristics****Figure 4 Rdson-JunctionTemperature****Figure 2 Transfer Characteristics****Figure 5 Gate Charge****Figure 3 Rdson- Drain Current****Figure 6 Source- Drift Diode Forward**

N-Channel MOSFET**2KK5050DFN****Figure 7 Capacitance vs Vds****Figure 9 Power De-rating****Figure 8 Safe Operation Area****Figure 10 Current De-rating****Figure 11 Normalized Maximum Transient Thermal Impedance**

N-Channel MOSFET

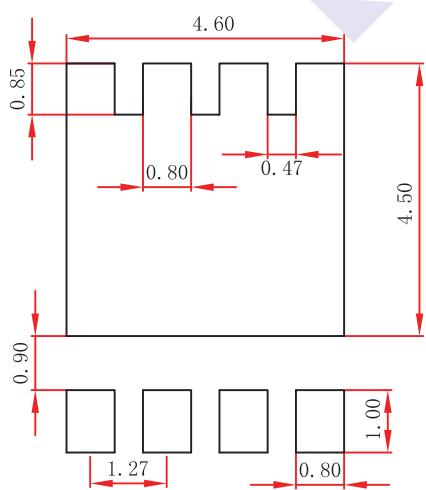
2KK5050DFN

■ DFN5x6-8(PDFNWB5x6-8L) Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF.		0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	10°	12°	10°	12°

■ DFN5x6-8(PDFNWB5x6-8L) Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.